LOCTITE®

Supplied by:
www.hitek-ltd.co.uk
+44 (0)1724 851678

HITEK
ELECTRONIC MATERIALS LTD

NASA OUTGASSING APPROVED PRODUCTS

Product	Description	TML %	CVCM %	WVR %	Testing Cure Schedule
84-1LMIT1	Low viscosity, high thermal conductivity, excellent adhesion to gold	0.12	0.01	0.09	2 hrs @ 125°C
8700E	High temperature resistance, high strength, excellent adhesion to gold	0.30	0.00	0.25	2 hrs @ 121°C
967-1	Low temperature cure	0.54	0.01	0.28	2 hrs @ 100°C
976-1	Flexible, low viscosity	0.71	0.10	0.28	1 hr @ 150°C
56C/Catalyst 9	Two component, room temperature cure	0.19	0.02	0.05	7 days @ 25°C
281	One component, good chemical resistance and electrical insulation	0.46	0.01	0.11	30 min @ 150°C
285/Catalyst 23LV	High bond strength, low CTE, room temperature cure	0.93	0.02	0.12	7 days @ 25°C
285/Catalyst 9	High bond strength, low CTE, room temperature cure	0.32	0.01	0.10	24 hrs @ 25°C
84-3	One component die attach adhesive	0.35	0.00	0.16	1 hr @ 150°C
8700K	One component, designed for hybrid component attach, excellent adhesion to gold	0.59	0.00	0.52	2 hrs @ 121°C
5025E	Ideal for RF power applications	0.30	0.06	0.08	1 hr @ 149°C
ECF561E	Flexible, high electrical conductivity	0.38	0.07	0.07	2 hrs @ 120°C
ECF568	Low temperature cure, superior adhesion to most surfaces	0.44	0.02	0.21	2 hrs @ 95°C
5020K	Superior adhesion to gold plated surfaces, designed for use in hermetic packages	0.24	0.02	0.18	1 hr @ 150°C
550	High strength for difficult to bond substrates	0.41	0.01	0.24	1 hr @ 150°C
550K	High strength for difficult to bond substrates, designed for heat sink attach	0.31	0.04	0.15	2 hrs @ 125°C
2651/Catalyst 23LV	Dielectric grade with excellent adhesion, thermal shock and impact resistance	0.66	0.03	0.11	24 hrs @ 25°C
2651MM/Catalyst 9	Low viscosity, non abrasive filler for machine dispense applications, room temperature cure	0.38	0.00	0.19	7 days @ 25°C
2850FT/Catalyst 23LV	Thermally conductive, low CTE, excellent electrically insulative properties	0.48	0.01	0.11	69 hrs @ 25°C
2850FT/Catalyst 9	Thermally conductive, low CTE, excellent electrically insulative properties, room temperature cure	0.25	0.01	0.08	24 hrs @ 25°C

TML: Total Mass Loss - CVCM: Collected Volatile Condensable Materials - WVR: Water Vapor Regained